



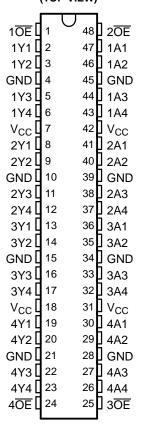
FEATURES

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JESD 70
- Typical V_{OLP} (Output Ground Bounce) <1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

DESCRIPTION

The SN54ABT16244 and SN74ABT16244A are 16-bit buffers and line drivers designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. These devices can be used as four 4-bit buffers, two 8-bit buffers, or one 16-bit buffer. These devices provide true outputs and symmetrical \overline{OE} (active-low output-enable) inputs.

SN54ABT16244... WD PACKAGE SN74ABT16244A... DGG, DGV, OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16244 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT16244A is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (EACH BUFFER)

INP	UTS	OUTPUT
ŌĒ	Α	Y
L	Н	Н
L	L	L
Н	X	Z



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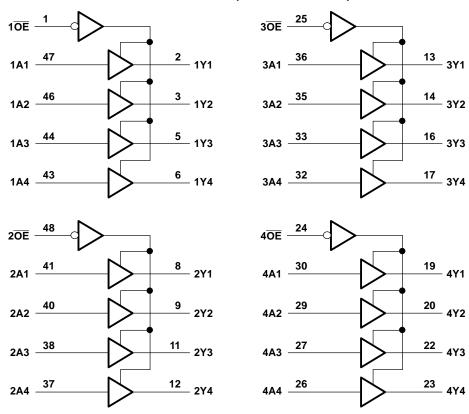


LOGIC SYMBOL⁽¹⁾ 1OE EN1 48 20E EN2 25 EN3 3OE 24 4OE EN4 47 2 1Y1 1A1 1 1 ▽ 46 3 1Y2 1A2 44 5 1A3 1Y3 43 6 1A4 1Y4 8 41 2 ▽ 2A1 1 2Y1 40 2A2 2Y2 38 11 2A3 2Y3 37 12 2A4 2Y4 36 13 3 ▽ 3A1 1 3Y1 35 14 3A2 3Y2 16 3A3 3Y3 32 17 3A4 3Y4 30 19 4A1 1 4 ▽ 4Y1 29 20 4A2 4Y2 27 22 4A3 4Y3 26 23 4A4 **4Y4**

(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V	
V_{I}	Input voltage range (2)	-0.5	7	V	
Vo	Voltage range applied to any output in the high or power-off state				V
Io	Current into any output in the law state	SN54ABT16244		96	A
	Current into any output in the low state	SN74ABT16244A		128	mA
I _{IK}	Input clamp current	V _I < 0		-18	mA
I_{OK}	Output clamp current	V _O < 0		-50	mA
		DGG package		89	
θ_{JA}	Package thermal impedance (3)	DGV package		93	°C/W
		DL package		94	
T _{stg}	Storage temperature range	-65	150	°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

⁽³⁾ The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD 51.

SN54ABT16244, SN74ABT16244A **16-BIT BUFFERS/DRIVERS** WITH 3-STATE OUTPUTS

SCBS073H-SEPTEMBER 1991-REVISED AUGUST 2005



Recommended Operating Conditions(1)

			SN54AB1	Г16244	SN74ABT	16244A	UNIT
			MIN	MAX	MIN	MAX	UNII
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V	
V_{IH}	High-level input voltage	2		2		V	
V_{IL}	Low-level input voltage		0.8		0.8	V	
V_{I}	Input voltage		0	V_{CC}	0	V_{CC}	V
I _{OH}	High-level output current			-24		-32	mA
I _{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
T_A	Operating free-air temperature	- 55	125	-40	85	°C	

All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T,	գ = 25°C ⁽	1)	SN54ABT16244		SN74ABT16244A			
		1551 60	RUITIONS	MIN	TYP ⁽²⁾	MAX	MIN	MAX	MIN	MAX	UNIT	
V_{IK}		$V_{CC} = 4.5 \text{ V},$	$I_I = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5		V	
V		V _{CC} = 5 V,	$I_{OH} = -3 \text{ mA}$	3			3		3			
V_{OH}		\/ 4 F \/	$I_{OH} = -24 \text{ mA}$	2			2				V	
		$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -32 \text{ mA}$	2(3)					2			
W		\/ 4.5.\/	I _{OL} = 48 mA			0.55		0.55			V	
V_{OL}		$V_{CC} = 4.5 \text{ V}$	I _{OL} = 64 mA			0.55(3)				0.55	V	
V _{hys}					100						mV	
I		$V_{CC} = 5.5 \text{ V}, V_{I} = V_{C}$	_{CC} or GND			±1		±1		±1	μΑ	
l _{OZH}		V _{CC} = 5.5 V,	V _O = 2.7 V			10 ⁽⁴⁾		10		10 ⁽⁴⁾	μΑ	
I _{OZL}		$V_{CC} = 5.5 \text{ V},$				-10 ⁽⁴⁾		-10		-10 ⁽⁴⁾	μΑ	
I _{off}		$V_{CC} = 0$,	V_I or $V_O \le 5.5 \text{ V}$			±100				±100	μΑ	
I _{CEX}		$V_{CC} = 5.5 \text{ V},$ $V_{O} = 5.5 \text{ V}$	Outputs high			50		50		50	μΑ	
I _O ⁽⁵⁾		$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			3		2		3		
I_{CC}		$I_{O} = 0$	Outputs low			32		32		32	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			3		2		3		
		$V_{CC} = 5.5 \text{ V},$	Outputs enabled			0.05		1.5		0.05		
$\Delta I_{CC}^{(6)}$	Data inputs	One input at 3.4 V, Other inputs at V _{CC} or GND	Outputs disabled			0.05		1		0.05	mA	
		V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				0.05		1.5		0.05		
C _i		V _I = 2.5 V or 0.5 V			3						pF	
Co		V _O = 2.5 V or 0.5 V			6						pF	

Characteristics for T_A = 25°C apply to the SN74ABT16244A only. All typical values are at V_{CC} = 5 V. On products compliant to MIL-PRF-38535, this parameter does not apply.

This data-sheet limit may vary among suppliers.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.





Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C	_{CC} = 5 V, \(= 25°C	•	MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A	· ·	0.7	2.3	3.2	0.7	3.6	ns
t _{PHL}	Α	ľ	0.5	2.6	3.7	0.5	4.2	115
t _{PZH}	<u>OE</u>	Υ	0.7	3	4	0.7	4.9	ns
t _{PZL}	OE	Ť		3.2	5.5	0.9	6.5	115
t _{PHZ}	<u>OE</u>	V	1.7	3.6	5	1.7	6	ns
t _{PLZ}	OL	I	1.5	2.9	4.7	1.5	5.7	115

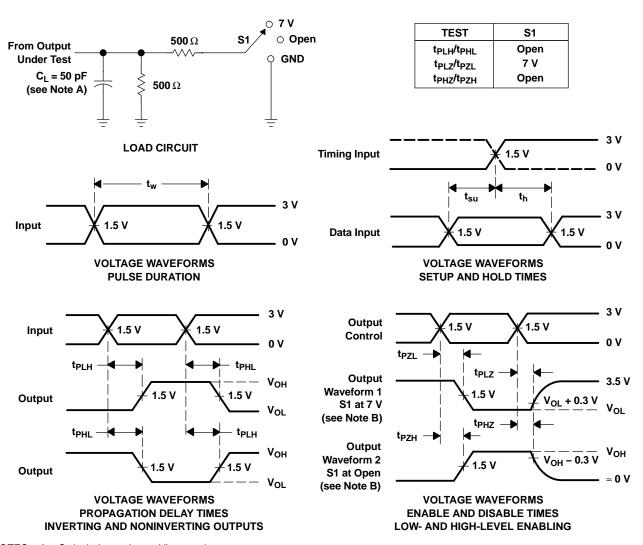
Switching Characteristics

over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

				SN74ABT16244A					
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₀	_{CC} = 5 V _A = 25°C	,	MIN	MAX	UNIT	
			MIN	TYP	MAX				
t _{PLH}	A D	Υ	1	2.3	3.2	1	3.5		
t _{PHL}	A or B	Ť	1	2.6	3.7	1	4.1	ns	
t _{PZH}	- ŌĒ	V	1	3	3.8	1	4.8	no	
t _{PZL}	- UE	Ť	1	3.2	4	1	4.8	ns	
t _{PHZ}	- ŌĒ	V	1	3.6	4.4	1	4.8	no	
t _{PLZ}	OE	T	1	2.9	3.7	1	4.1	ns	



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





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PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9317401MXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC
74ABT16244ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT16244ADGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16244ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16244ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16244ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16244ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16244ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT16244ADLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT16244WD	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

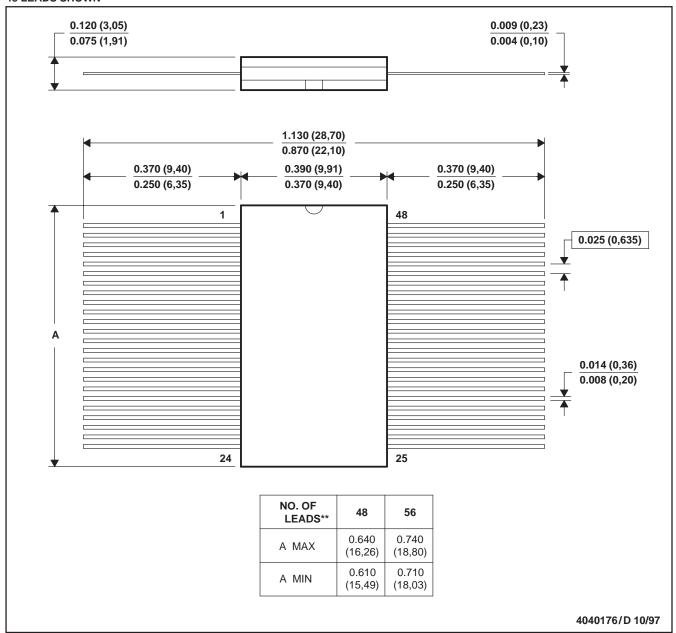
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WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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